

Electronic Patent Application Fee Transmittal

Application Number:	10810965				
Filing Date:	26-Mar-2004				
Title of Invention:	Novel method to improve bump reliability for flip chip device				
First Named Inventor/Applicant Name:	Yen-Ming Chen				
Filer:	Daniel R. McClure				
Attorney Docket Number:	TS01-0413C				
Filed as Large Entity					
Utility Filing Fees					
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:					
Pages:					
Claims:					
Miscellaneous-Filing:					
Petition:					
Patent-Appeals-and-Interference:					
Filing a brief in support of an appeal		1402	1	500	500
Post-Allowance-and-Post-Issuance:					
Extension-of-Time:					

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				500